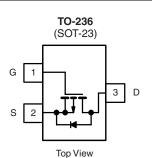


P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^d	Q _g (Typ.)			
- 60	0.345 at V _{GS} = - 10 V	- 1.6	2.7 nC			
	0.450 at V _{GS} = - 4.5 V	- 1.4	2.7 110			



Si2309CDS (N9)*

* Marking Code

Ordering Information: Si2309CDS-T1-E3 (Lead (Pb)-free)

Si2309CDS-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

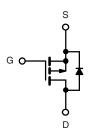
- Halogen-free Option Available
- TrenchFET® Power MOSFET



RoHS

APPLICATIONS

· Load Switch



P-Channel MOSFET

Parameter		Symbol	Limit	Uni	
Drain-Source Voltage	V _{DS}	- 60	V		
Gate-Source Voltage		V _{GS}		± 20	
	T _C = 25 °C		- 1.6		
0 11 0 1 0 1 7 1 1 2 2 2 3 h	T _C = 70 °C		- 1.3		
Continuous Drain Current (T _J = 150 °C) ^{a, b}	T _A = 25 °C	I _D	- 1.2 ^{a, b}		
	T _A = 70 °C		- 1.0 ^{a, b}	_	
Pulsed Drain Current (10 µs Pulse Width)		I _{DM}	- 8	_ A	
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	- 5		
	T _C = 25 °C	1	- 1.4		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 0.9 ^{a, b}		
	T _C = 25 °C		1.7		
	T _C = 70 °C	В	1.1	101	
Maximum Power Dissipation	T _A = 25 °C	P _D	1.0 ^{a, b}	W	
	T _A = 70 °C		0.67 ^{a, b}		
Operating Junction and Storage Temperature Rar	T _J , T _{stg}	- 55 to 150	90		
Soldering Recommendations (Peak Temperature)		260	- °C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{a, c}	t ≤ 5 s	R_{thJA}	92	120	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	58	73	C/VV		

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. t = 5 s.

c. Maximum under Steady State conditions is 166 °C/W.

d. When T_C = 25 °C.

Si2309CDS

Vishay Siliconix



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, I}_{D} = -250 \mu\text{A}$	- 60			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 65		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	Ι _D = - 230 μΑ		4.5			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			- 100	nA	
Zara Cata Valtaga Drain Current	I _{DSS}	V _{DS} = - 60 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current		V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 55 °C			- 10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5 \text{ V}, V_{GS} = -10 \text{ V}$	- 6			Α	
	_	V _{GS} = - 10 V, I _D = - 1.25 A		0.285	0.345		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 1.0 A		0.360	0.450	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 1.0 A		2.8		S	
Dynamic ^b	1			I	L		
Input Capacitance	C _{iss}			210		pF	
Output Capacitance	C _{oss}	V _{DS} = - 30 V, V _{GS} = 0 V, f = 1 MHz		28			
Reverse Transfer Capacitance	C _{rss}			20			
Total Gate Charge	Qg			2.7	4.1	nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = -30 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -1.25 \text{ A}$		0.8			
Gate-Drain Charge	Q_{gd}			1.2			
Gate Resistance	R_{g}	f = 1 MHz		7		Ω	
Turn-On Delay Time	t _{d(on)}			40	60		
Rise Time	t _r	V_{DD} = - 30 V, R_L = 30 Ω		35	55		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		15	25		
Fall Time	t _f			10	20		
Turn-On Delay Time	t _{d(on)}			5	10	ns	
Rise Time	t _r	V_{DD} = - 30 V, R_L = 30 Ω		10	20		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 10 V, R_g = 1 Ω		15	25		
Fall Time	t _f			10	20		
Drain-Source Body Diode Characteris	tics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 1.4	Α	
Pulse Diode Forward Current	I _{SM}				- 8	^	
Body Diode Voltage	V_{SD}	I _S = - 0.75 A, V _{GS} = 0 V		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			30	60	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	 I _F = - 1.25 A, dl/dt = 100 A/μs, T _J = 25 °C		33	60	nC	
everse Recovery Fall Time t _a		η - 1.20 Λ, αι/αι - 100 Λ/μο, 1 J - 20 0		18		no	
Reverse Recovery Rise Time	t _b	[12		ns	

Notes:

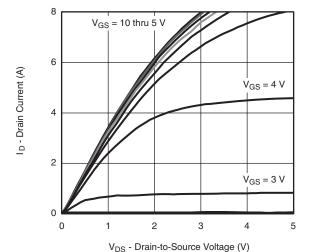
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

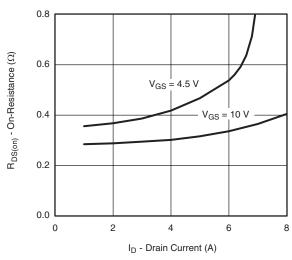
b. Guaranteed by design, not subject to production testing.



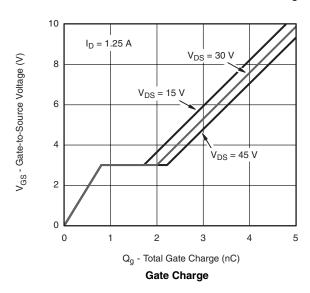
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



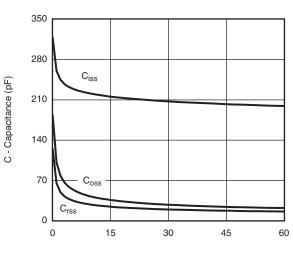
Output Characteristics



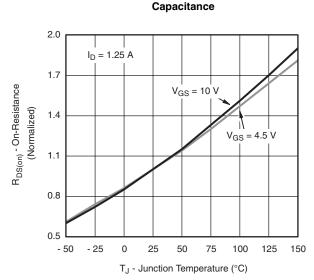
On-Resistance vs. Drain Current and Gate Voltage



V_{GS} - Gate-to-Source Voltage (V) **Transfer Characteristics**



V_{DS} - Drain-to-Source Voltage (V)

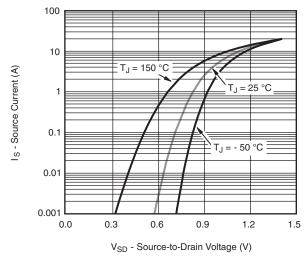


Si2309CDS

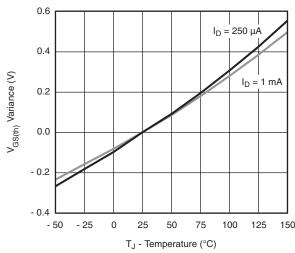
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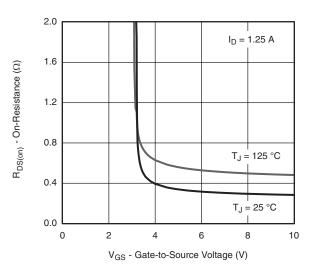
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



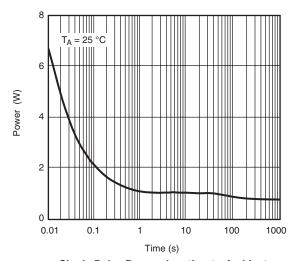
Source-Drain Diode Forward Voltage



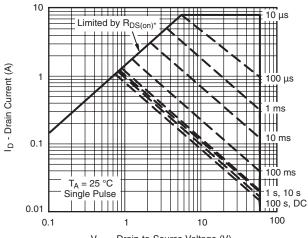
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



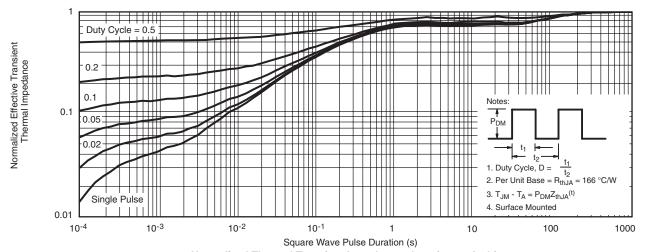
V_{DS} - Drain-to-Source Voltage (V)

* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

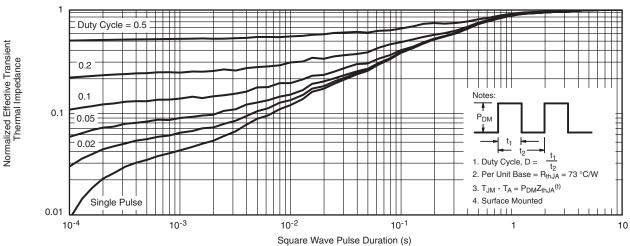
Safe Operating Area, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOT-23 (TO-236): 3-LEAD







Dim	MILLIMETERS		INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.9	0 BSC	0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
FCN: S-03946-Rev K 09-	lul-01	•			

ECN: S-03946-Rev. K, 09-Jul-01

DWG: 5479

Document Number: 71196 www.vishay.com 09-Jul-01



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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